Preferred Device

# Sensitive Gate Silicon Controlled Rectifiers

# **Reverse Blocking Thyristors**

PNPN devices designed for high volume, low cost consumer applications such as temperature, light and speed control; process and remote control; and warning systems where reliability of operation is critical.

### Features

- Pb–Free Package is Available
- Small Size
- Passivated Die Surface for Reliability and Uniformity
- Low Level Triggering and Holding Characteristics
- Recommend Electrical Replacement for C106
- Surface Mount Package Case 369C
- To Obtain "DPAK" in Straight Lead Version (Shipped in Sleeves): - Add '1' Suffix to Device Number, i.e., MCR706A1
- Epoxy Meets UL 94, V-0 @ 0.125 in
- ESD Ratings: Human Body Model, 3B > 8000 V Machine Model, C > 400 V



### ON Semiconductor®

http://onsemi.com

SCRs 4.0 AMPERES RMS 100 – 600 VOLTS



MARKING DIAGRAMS





Y = Year WW = Work Week x = 3, 6, or 8

PIN ASSIGNMENT			
1 Gate			
2	Anode		
3	Cathode		
4 Anode			

#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 3 of this data sheet.

**Preferred** devices are recommended choices for future use and best overall value.

### **MAXIMUM RATINGS** (T<sub>J</sub> = $25^{\circ}C$ unless otherwise noted)

Rating	Symbol	Max	Unit
MCI	VDRM, R703A V <sub>RRM</sub> R706A R708A	100 400 600	V
MCI	V <sub>RSM</sub> R703A R706A R708A	150 450 650	V
On–State RMS Current (180° Conduction Angles; T <sub>C</sub> = 90°C)	I <sub>T(RMS)</sub>	4.0	A
Average On-State Current (180° Conduction Angles) $T_C = -40$ to +90°C $T_C = +100°C$	I <sub>T(AV)</sub>	2.6 1.6	A
Non-Repetitive Surge Current (1/2 Sine Wave, 60 Hz, $T_J = 110^{\circ}$ C) (1/2 Sine Wave, 1.5 ms, $T_J = 110^{\circ}$ C)	I <sub>TSM</sub>	25 35	A
Circuit Fusing (t = 8.3 msec)	l <sup>2</sup> t	2.6	A <sup>2</sup> sec
Forward Peak Gate Power (Pulse Width $\leq$ 1.0 µsec, T <sub>C</sub> = 90°C)	P <sub>GM</sub>	0.5	W
Forward Average Gate Power $(t = 8.3 \text{ msec}, T_C = 90^{\circ}\text{C})$	P <sub>G(AV)</sub>	0.1	W
Forward Peak Gate Current (Pulse Width $\leq$ 1.0 µsec, T <sub>C</sub> = 90°C)	I <sub>GM</sub>	0.2	A
Operating Junction Temperature Range	TJ	-40 to +110	°C
Storage Temperature Range	T <sub>stg</sub>	-40 to +150	°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

V<sub>DRM</sub> and V<sub>RRM</sub> for all types can be applied on a continuous basis. Ratings apply for zero or negative gate voltage; however, positive gate voltage shall not be applied concurrent with negative potential on the anode. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.

#### THERMAL CHARACTERISTICS

Characteristic		Max	Unit
Thermal Resistance, Junction-to-Case	$R_{ extsf{ heta}JC}$	8.33	°C/W
Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\thetaJA}$	80	°C/W
Maximum Lead Temperature for Soldering Purposes 1/8" from Case for 10 Seconds	ΤL	260	°C

2. Case 369C when surface mounted on minimum pad sizes recommended.

### **ELECTRICAL CHARACTERISTICS** (T<sub>C</sub> = $25^{\circ}$ C unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit	
DFF CHARACTERISTICS		-				-
Peak Repetitive Forward or Reverse Blocking Curre $(V_{AK} = Rated V_{DRM} \text{ or } V_{RRM}; R_{GK} = 1 \text{ K}\Omega)$	ent T <sub>C</sub> = 25°C T <sub>C</sub> = 110°C	I <sub>DRM</sub> , I <sub>RRM</sub>			10 200	μΑ
ON CHARACTERISTICS		-				-
Peak Forward "On" Voltage (I <sub>TM</sub> = 8.2 A Peak, Pulse Width = 1 to 2 ms, 2% D	Outy Cycle)	V <sub>TM</sub>	_	-	2.2	V
Gate Trigger Current (Continuous dc) (Note 3) (V <sub>AK</sub> = 12 Vdc, R <sub>L</sub> = 24 Ohms)	$T_C = 25^{\circ}C$ $T_C = -40^{\circ}C$	I <sub>GT</sub>		25 -	75 300	μΑ
Gate Trigger Voltage (Continuous dc) (Note 3) $(V_{AK} = 12 \text{ Vdc}, R_L = 24 \text{ Ohms})$	$T_{C} = 25^{\circ}C$ $T_{C} = -40^{\circ}C$	V <sub>GT</sub>	-	-	0.8 1.0	V
Gate Non-Trigger Voltage (Note 3) ( $V_{AK}$ = 12 Vdc, $R_L$ = 100 Ohms, $T_C$ = 110°C)		V <sub>GD</sub>	0.2	_	—	V
Holding Current (V <sub>AK</sub> = 12 Vdc, Gate Open) (Initiating Current = 200 mA)	$T_C = 25^{\circ}C$ $T_C = -40^{\circ}C$	Чн			5.0 10	mA
Peak Reverse Gate Blocking Voltage $(I_{GR} = 10 \ \mu A)$		V <sub>RGM</sub>	10	12.5	18	V
Peak Reverse Gate Blocking Current (V <sub>GR</sub> = 10 V)		I <sub>RGM</sub>	_	-	1.2	μΑ
Total Turn-On Time (Source Voltage = 12 V, $R_S = 6 k\Omega$ ) ( $I_{TM} = 8.2 A$ , $I_{GT} = 2 mA$ , Rated $V_{DRM}$ ) (Rise Time = 20 ns, Pulse Width = 10 µs)		t <sub>gt</sub>	_	2.0	_	μs
DYNAMIC CHARACTERISTICS						
Critical Rate of Rise of Off–State Voltage $(V_D = Rated V_{DRM}, R_{GK} = 1 \text{ k}\Omega, \text{ Exponential Wave}$ $T_C = 110^{\circ}C)$	veform,	dv/dt	-	10	-	V/µs
Repetitive Critical Rate of Rise of On–State Current (Cf = 60 Hz, $I_{PK}$ = 30 A, PW = 100 $\mu$ s, diG/dt = 1		di/dt	-	-	100	A/μs

3.  $R_{GK}$  current not included in measurement.

### **ORDERING INFORMATION**

Device	Package Type	Package	Shipping <sup>†</sup>
MCR703AT4	DPAK	369C	2500 Tape & Reel
MCR706AT4	DPAK	369C	2500 Tape & Reel
MCR706AT4G	DPAK (Pb–Free)	369C	2500 Tape & Reel
MCR708A	DPAK	369C	2500 Tape & Reel
MCR708A1	DPAK-3	369D	75 Units / Rail
MCR708AT4	DPAK	369C	2500 Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

### Voltage Current Characteristic of SCR

			+ Cu	irrent	Anod	le +
Sym	bol Parameter			└ ◄─∨ <sub>тм</sub>		
V <sub>DRM</sub>				↓ VIM		
I <sub>DRM</sub>	Peak Forward Blocking Current		on state	<u> </u> .		
V <sub>RRM</sub>		I <sub>RRM</sub> at V <sub>RRM</sub>	1	<u> </u>		
I <sub>RRM</sub>	Peak Reverse Blocking Current					<u>د</u>
V <sub>TM</sub>	Peak On–State Voltage		4		· /	+ Voltage
Ι <sub>Η</sub>	Holding Current	Reverse B	locking Region		I <sub>DRM</sub> at V <sub>E</sub>	-
			f state) lanche Region		Blocking Regi	on
		P(AV), AVERAGE POWER DISSIPATION (WATTS) 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0				
	30°C	ZO 4.0				30°C 60°C
105	00°C					90°C
		; SG 3.0				120°C
	180°C				\//	180°C
	DC	on 2.0				DC
100		GE I		XI.	$\sim$	
		He 1.0		I		
		), AV				
95						
0	1.0 2.0 3.0 4.0	5.0	0 1.0	2.0	3.0	4.0 5.0
	I <sub>T(AV)</sub> , AVERAGE ON-STATE CURRENT (AMPS)		I <sub>T(AV)</sub> , AVE	RAGE ON-ST	ATE CURRENT	(AMPS)
	Figure 1. Average Current Derating		Figure 2.	On-State	Power Diss	sipation
100	Typical @ T <sub>J</sub> = 25°C	<u><u> </u></u>				
Ē						
	Maximum @ T <sub>J</sub> = 110°C	RMA				
10		NO N			Z <sub>0</sub> JC(	$\mathbf{t}_{t} = \mathbf{R}_{\Theta \mathbf{JC}(t)} \bullet \mathbf{r}(t)$
Ĩ		NCE				
		TS 0.1				
	Maximum @ T <sub>J</sub> = 25°C	HESI				
1.0		(t), TRANSIENT RESISTANCE (NORMALIZED)				
		TRA				
0.1		Ê 0.01				
0.5	1.0 1.5 2.0 2.5 3.0 3.5 4.0		0.1 1.0	10	100	1000 10,000
	$V_{T}$ , INSTANTANEOUS ON-STATE VOLTAGE (VOLTS)			t, TIME	(ms)	
	Figure 3. On–State Characteristics		Figure 4.	Fransient <sup>-</sup>	Thermal Re	sponse

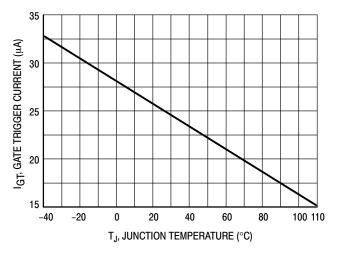


Figure 5. Typical Gate Trigger Current versus Junction Temperature

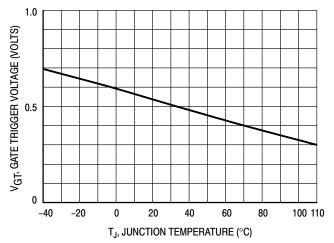


Figure 6. Typical Gate Trigger Voltage versus Junction Temperature

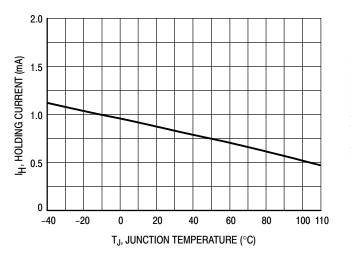


Figure 7. Typical Holding Current versus Junction Temperature

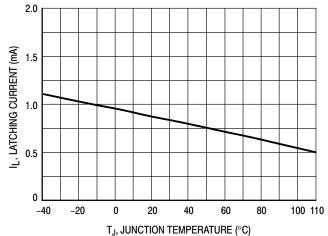
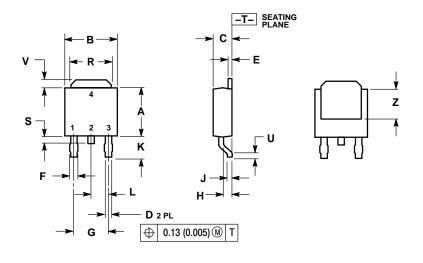


Figure 8. Typical Latching Current versus Junction Temperature

#### PACKAGE DIMENSIONS



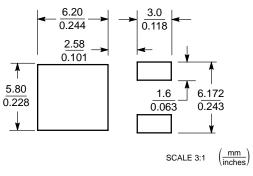


NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH.

	INC	HES	MILLIN	IETERS	
DIM	MIN MAX		MIN	MAX	
Α	0.235	0.245	5.97	6.22	
В	0.250	0.265	6.35	6.73	
С	0.086	0.094	2.19	2.38	
D	0.027	0.035	0.69	0.88	
Е	0.018	0.023	0.46	0.58	
F	0.037	0.045	0.94	1.14	
G	0.180 BSC		4.58 BSC		
Н	0.034	0.040	0.87	1.01	
J	0.018	0.023	0.46	0.58	
κ	0.102	0.114	2.60	2.89	
L	0.090	BSC	2.29	BSC	
R	0.180	0.215	4.57	5.45	
S	0.025	0.040	0.63	1.01	
U	0.020		0.51		
V	0.035	0.050	0.89	1.27	
Ζ	0.155		3.93		

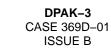
STYLE 2: PIN 1. GATE 2. DRAIN 3. SOURCE 4. DRAIN

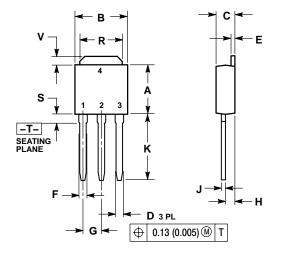
#### **SOLDERING FOOTPRINT\***

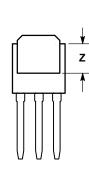


\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

### PACKAGE DIMENSIONS







NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH.

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DIM	MIN	MAX	MIN	MAX
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Е	0.018	0.023	0.46	0.58
F	0.037	0.045	0.94	1.14
G	0.090	0.090 BSC 2.29 BSC		
Н	0.034	0.040	0.87	1.01
J	0.018	0.023	0.46	0.58
κ	0.350	0.380	8.89	9.65
R	0.180	0.215	4.45	5.45
S	0.025	0.040	0.63	1.01
٧	0.035	0.050	0.89	1.27
Ζ	0.155		3.93	

STYLE 2: PIN 1. GATE 2. DRAIN 3. SOURCE 4. DRAIN

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